

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

NAVEED MAJID ET AL

Serial No. 09/440,595

Filed: NOVEMBER 15, 1999

Atty. Docket

PHA 23,843

Group Art Unit: 2811

Examiner: N. PAREKH



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Jens
3/16/01

MULTIPLE SEMICONDUCTOR CHIP (MULTI-CHIP) MODULE FOR USE IN HIGH-POWER APPLICATIONS

Commissioner for Patents
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. 1.97

Sir:

Enclosed is a Form PTO-1449 and copies of documents listed thereon. These documents are considered to be relevant in that they have been:

- ☐ considered in drafting the specification of the above-referenced application;
- ☐ cited in the specification of the above-referenced application; or
- ☒ cited as an "X" or "Y" document in a foreign Patent Office search report on a foreign counterpart application a copy of which report is also enclosed.

☒ I hereby certify that these documents were cited in said search report not more than three (3) months ago.

☐ Please charge any fee under 1.17(p) for this Information Disclosure Statement to be considered, not exceeding \$240.00, to Account No. 14-1270.

If readily available, English-language counterparts have been substituted for foreign-language patent documents. This disclosure is not an admission that any of these documents is material to or even prior art with respect to the above-referenced application.

Respectfully submitted,

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